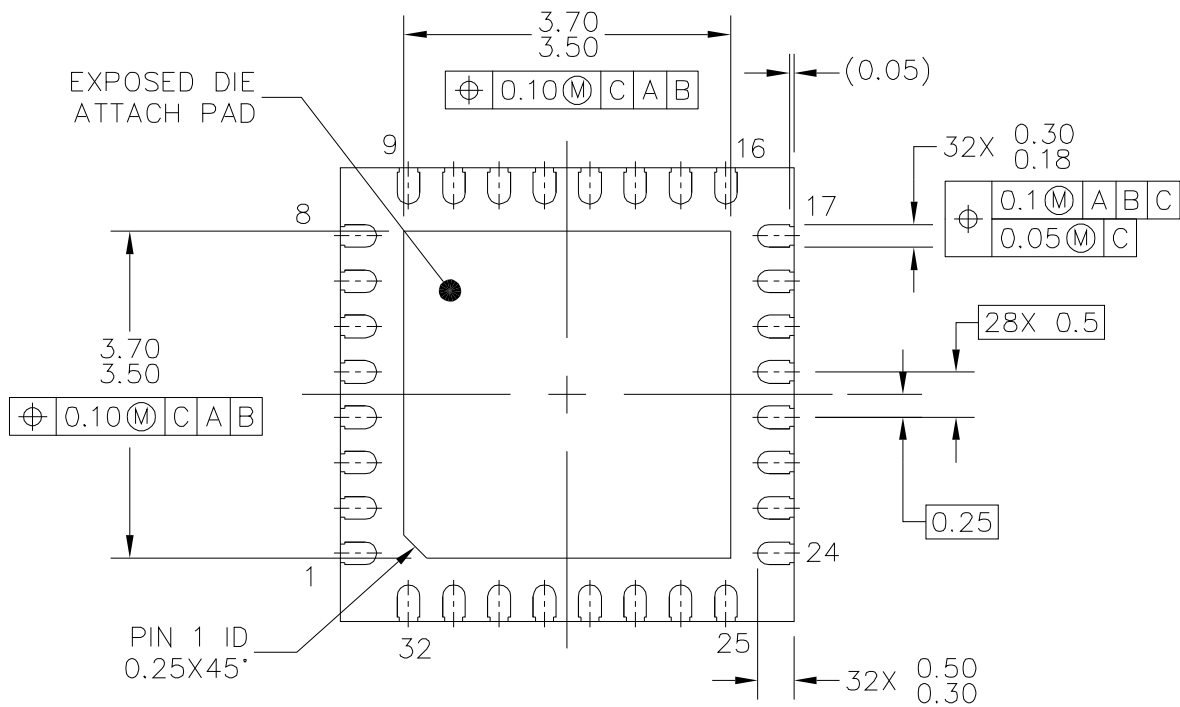
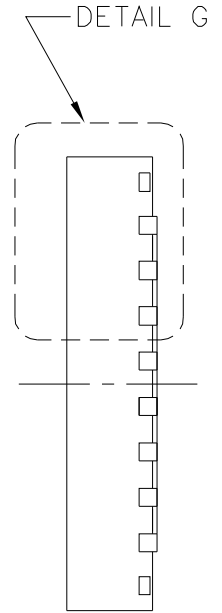
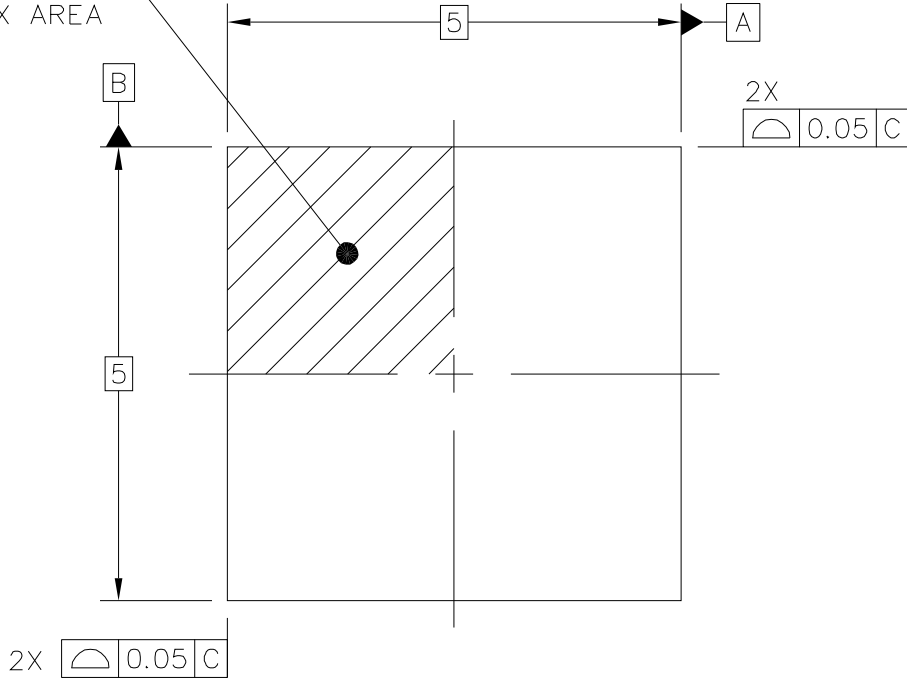


PIN 1  
INDEX AREA



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**MECHANICAL OUTLINE**

PRINT VERSION NOT TO SCALE

TITLE:  
QFN, THERMALLY ENHANCED  
5 X 5 X 0.9, 0.5 PITCH, 32 TERMINAL

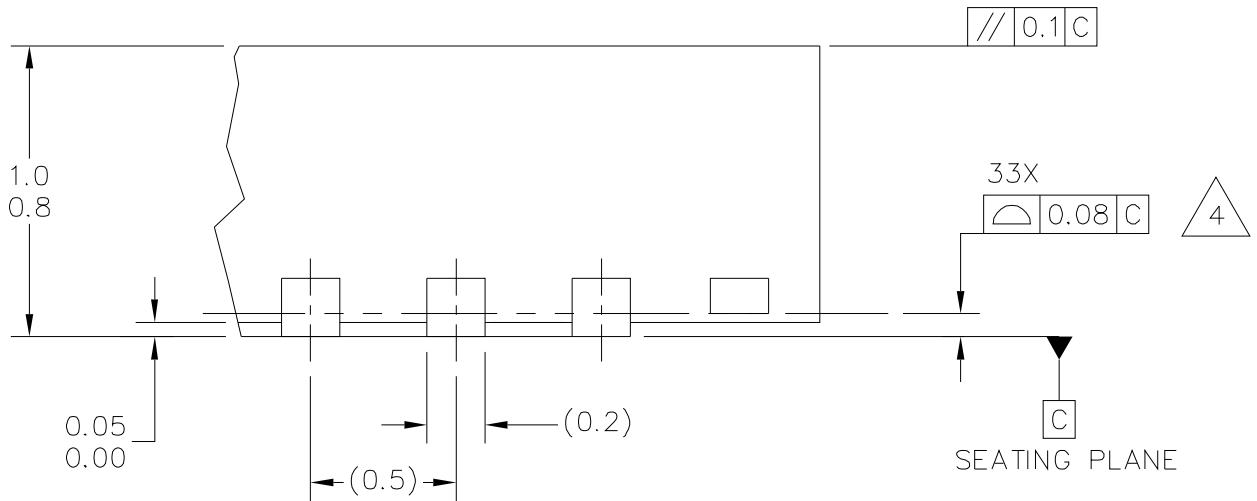
DOCUMENT NO: 98ASA00473D

REV: A

CASE NUMBER: 2295-02

11 OCT 2012


STANDARD: NON-JEDEC



DETAIL G  
VIEW ROTATED 90°CW

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TITLE: QFN, THERMALLY ENHANCED 5 X 5 X 0.9, 0.5 PITCH, 32 TERMINAL		DOCUMENT NO: 98ASA00473D	REV: A
		CASE NUMBER: 2295-02	11 OCT 2012
		STANDARD: NON-JEDEC	

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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TITLE: QFN, THERMALLY ENHANCED 5 X 5 X 0.9, 0.5 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00473D	REV: A	
	CASE NUMBER: 2295-02	11 OCT 2012	
	STANDARD: NON-JEDEC		